imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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3A, 50V - 1000V Surface Mount Rectifier

FEATURES

TAIWAN

• Glass passivated chip junction

SEMICONDUCTOR

- Ideal for automated placement
- Low forward voltage drop
- High current capability
- High surge current capability
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

MECHANICAL DATA

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Part no. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.21 g (approximately)

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
I _{F(AV)}	3	А			
V _{RRM}	50 - 1000	V			
I _{FSM}	100	А			
T _{J MAX}	150	°C			
Package	DO-214AB (SMC)				
Configuration	Single die				





DO-214AB (SMC)

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)									
PARAMETER	SYMBOL	S3A	S3B	S3D	S3G	S3J	S3K	S3M	UNIT
Marking code on the device		S3A	S3B	S3D	S3G	S3J	S3K	S3M	
Repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Forward current	I _{F(AV)}				3				А
Surge peak forward current, 8.3 ms single half sine-wave uperimposed on rated load per diode	I _{FSM}	100			A				
Junction temperature	T_J	T _J - 55 to +150			°C				
Storage temperature	T _{STG}	T _{STG} - 55 to +150			°C				



apability



THERMAL PERFORMANCE						
PARAMETER	SYMBOL	LIMIT	UNIT			
Junction-to-lead thermal resistance per diode	R _{eJL}	13	°C/W			
Junction-to-ambient thermal resistance per diode	R _{eJA}	47	°C/W			

ELECTRICAL SPECIFICATIONS ($T_A = 25^{\circ}C$ unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	TYP.	MAX.	UNIT	
Forward voltage per diode (1)	$I_F = 3A, T_J = 25^{\circ}C$	V _F	-	1.15	V	
	T _J = 25°C		-	10	μA	
Reverse current @ rated V_R per diode ⁽²⁾	T _J = 125°C	I _R	-	250	μA	
Junction capacitance	1 MHz, V _R =4.0V	CJ	60	-	pF	
Reverse recovery time	I _F =0.5A , I _R =1.0A I _{RR} =0.25A	+	1500		20	
	I _{RR} =0.25A	t _{rr}	1500	-	ns	

Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

ORDERING	ORDERING INFORMATION						
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING		
	н	R7		SMC	850 / 7" Plastic reel		
		R6	G	SMC	3,000 / 13" Paper reel		
S3x (Note 1)		M6		SMC	3,000 / 13" Plastic reel		
		V7		Matrix SMC	850 / 7" Plastic reel		
		V6		Matrix SMC	3,000 / 13" Plastic reel		

Note :

1. "x" defines voltage from 50V (S3A) to 1000V (S3M)

EXAMPLE					
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
S3AHR7G	S3A	Н	R7	G	AEC-Q101 qualified Green compound



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

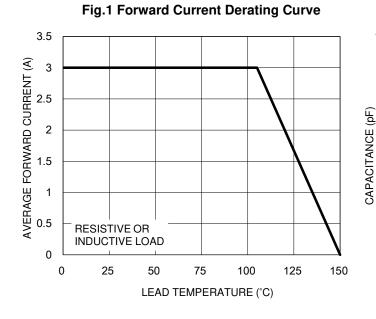


Fig.2 Typical Junction Capacitance



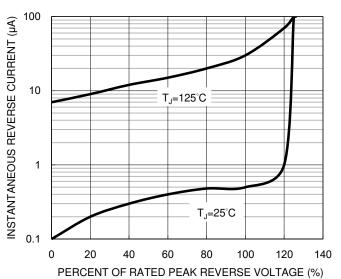
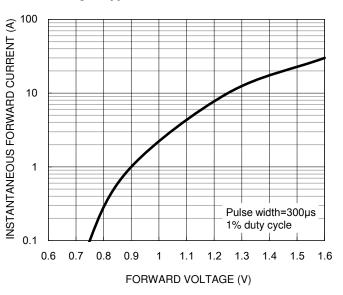


Fig.4 Typical Forward Characteristics





CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

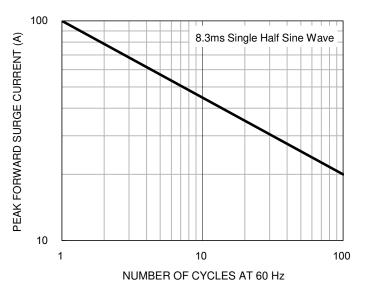
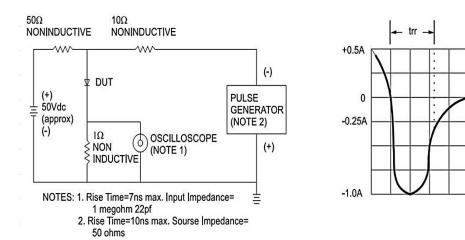


Fig.5 Maximum Non-repetitive Forward Surge Current

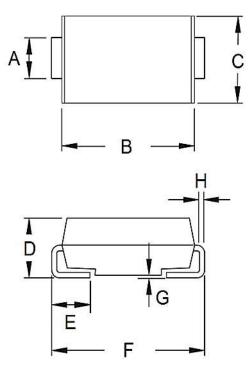






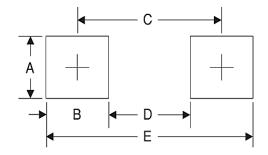
PACKAGE OUTLINE DIMENSIONS

DO-214AB (SMC)



DIM.	Unit	(mm)	Unit (inch)		
DIM.	Min	Max	Min	Max	
Α	2.90	3.20	0.114	0.126	
В	6.60	7.11	0.260	0.280	
С	5.59	6.22	0.220	0.245	
D	2.00	2.62	0.079	0.103	
E	1.00	1.60	0.039	0.063	
F	7.75	8.13	0.305	0.320	
G	0.10	0.20	0.004	0.008	
Н	0.15	0.31	0.006	0.012	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
А	3.30	0.130
В	2.50	0.098
С	6.80	0.268
D	4.40	0.173
E	9.40	0.370

MARKING DIAGRAM



- P/N =Marking Code
- G =Green Compound
- YW =Date Code
- F =Factory Code



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